



SEMI E10-0600

SPECIFICATION FOR DEFINITION AND MEASUREMENT OF EQUIPMENT RELIABILITY, AVAILABILITY, AND MAINTAINABILITY (RAM)

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1 Purpose

1.1 This document establishes a common basis for communication between users and suppliers of semiconductor manufacturing equipment by providing standards for measuring RAM performance of that equipment in a manufacturing environment.

2 Scope

2.1 The document defines six basic equipment states into which all equipment conditions and periods of time must fall. The equipment states are determined by functional issues, independent of who performs the function. The measurement of equipment reliability in this specification concentrates on the relationship of equipment interrupts to equipment usage, rather than the relationship of failures to total elapsed time.

2.2 Section 5 (Equipment States) defines how equipment time is categorized. Section 6 (RAM Measurement) defines formulas for measurement of equipment performance. Section 7 (Uncertainty Measurement) gives additional methods for evaluating the statistical significance of calculated performance metrics.

2.3 Effective application of this specification requires that equipment performance (RAM) be tracked with regard to time and/or equipment cycles. Automated tracking of equipment states is not within the scope of this specification, but is covered by SEMI E58. Clear and effective communication among users and suppliers promotes continuous improvement in equipment performance.

2.4 The RAM indices in this specification may be applied directly to non-cluster tools at the whole equipment and sub-system levels. The RAM indices may be applied at the sub-system level (e.g., process module) for multi-path cluster tools.

2.5 This standard does not purport to address safety issues, if any, associated with its use. It is the responsibility of the users of this standard to establish appropriate safety and health practices and determine the applicability of regulatory limitations prior to use.

3 Referenced Standards

SEMI E58 — Automated Reliability, Availability, and Maintainability Standard (ARAMS)

NOTE 1: As listed or revised, all documents cited shall be the latest publications of adopted standards.

4 Terminology

4.1 *assist* — an unplanned interruption that occurs during an equipment cycle where all three of the following conditions apply:

- The interrupted equipment cycle is resumed through external intervention (e.g., by an operator or user, either human or host computer).
- There is no replacement of a part, other than specified consumables.
- There is no further variation from specifications of equipment operation.

4.2 *cluster tool* — a manufacturing system made up of integrated processing modules mechanically linked together (the modules may or may not come from the same supplier).

4.2.1 *single path cluster tool* — a cluster tool with only one process flow path (as used).

4.2.2 *multi-path cluster tool* — a cluster tool with more than one independent process flow path (e.g., multiple load ports/load-locks, multiple process chambers of the same type) and used as such.

4.3 *cycle (equipment cycle)* — one complete operational sequence (including product load and unload) of processing, manufacturing, or testing steps for an equipment system or subsystem. In single unit processing systems, the number of cycles equals the number of units processed. In batch systems, the number of cycles equals the number of batches processed.

4.4 *downtime (equipment downtime)* — the time when the equipment is not in a condition, or is not available,



to perform its intended function. It does not include any portion of non-scheduled time.

4.5 *failure (equipment failure)* — any unplanned interruption or variance from the specifications of equipment operation other than assists.

NOTE 2: It may be important to categorize and qualify failures in ways that facilitate the resolution of problems and improve overall equipment performance (see Application Note 2).

4.6 *host* — the intelligent system which communicates with the equipment, and acts as a supervisory agent, which represents the factory to its subordinates (e.g., non-embedded computer or cell controller).

4.7 *interrupt* — any assist or failure.

NOTE 3: interrupts = sum of # assists + sum of # failures

4.8 *maintenance* — the act of sustaining equipment in or restoring it to a condition to perform its intended function. In this document, maintenance refers to function, not organization; it includes adjustments, change of consumables, software upgrades, repair, preventive maintenance, etc., no matter who performs the task.

4.9 *manufacturing time* — the sum of productive time and standby time.

4.10 *non-scheduled time* — a period when the equipment is not scheduled to be utilized in production.

4.11 *operations time* — total time minus non-scheduled time.

4.12 *operator* — any person who communicates locally with the equipment through the equipment's control panel.

4.13 *product* — any unit which is intended to become a functional semiconductor device. This includes functional engineering devices.

4.14 *ramp-down* — the portion of a maintenance procedure required to prepare the equipment for hands-on work. It includes purging, cool-down, warm-up, software backup, storing dynamic values (e.g., parameters, recipes), etc. Ramp-down is only included in scheduled and unscheduled downtime.

4.15 *ramp-up* — the portion of a maintenance procedure required, after the hands-on work is completed, to return the equipment to a condition where it can perform its intended function. It includes pump down, warm-up, stabilization periods, initialization routines, software load, restoring dynamic values (e.g., parameters, recipes), control system reboot, etc. It does not include equipment or process test time. Ramp-up is only included in scheduled and unscheduled downtime.

4.16 *shutdown* — the time required to put the equipment in a safe condition when entering a non-scheduled state. It includes any procedures necessary to reach a safe condition. Shutdown is only included in non-scheduled time.

4.17 *specification (equipment operation)* — the documented set of intended functions within stated conditions for equipment operation as agreed upon between user and supplier.

4.18 *start-up* — the time required for equipment to achieve a condition where it can perform its intended function, when leaving a non-scheduled state. It includes pump down, warm-up, cool-down, stabilization periods, initialization routines, software load, restoring dynamic values (e.g., parameters, recipes), control system reboot, etc. Start-up is only included in non-scheduled time.

4.19 *support tool* — a device that, although not part of a piece of equipment, is required by, and becomes integral with it during the course of normal operation (e.g., cassettes, wafer carriers, probe cards, computerized controllers / monitors).

4.20 *total time* — all time (at the rate of 24 hrs/day, 7 days/week) during the period being measured. In order to have a valid representation of total time, all six basic equipment states must be accounted for and tracked accurately.

4.21 *training (off-line)* — the instruction of personnel in the operation and/or maintenance of equipment done outside of operations time. Off-line training is only included in non-scheduled time.

4.22 *training (on-the-job)* — the instruction of personnel in the operation and/or maintenance of equipment done during the course of normal work functions. On-the-job training typically does not interrupt operation or maintenance activities and can therefore be included in any equipment state (except standby and non-scheduled) without special categorization.

4.23 *unit* — any wafer, die, packaged device, or piece part thereof (includes product and non-product units).

4.24 *uptime (equipment uptime)* — the hours when the equipment is in a condition to perform its intended function. It includes productive, standby, and engineering time, and does not include any portion of non-scheduled time.

4.25 *user* — any entity interacting with the equipment, either locally as an operator or remotely via the automation interface. From the equipment's view point, both the operator and the host represent the user.



4.26 *verification run* — a single cycle of the equipment (using product units, non-product units or no units) used to establish that it is performing its intended function within specifications.

5 Equipment States

5.1 To clearly measure equipment performance (RAM), this document defines six basic equipment states into which all equipment conditions and periods of time must fall.

5.2 The equipment states are determined by function, not by organization. Any given maintenance procedure, for example, is classified the same way no matter who performs it, an operator, a production technician, a maintenance technician, or a process engineer.

5.3 Figure 1 is a stack chart of the six basic equipment states. Key blocks of time are identified for use in equations given later in this document. These basic equipment states can be divided into as many sub-states as are required to achieve the equipment tracking resolution that a manufacturing operation desires. SEMI E10 makes no attempt to list all possible sub-states, but does give some examples for guidance.

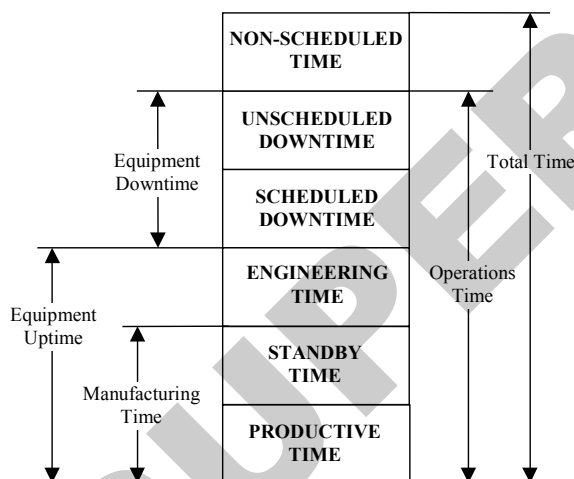


Figure 1
Equipment States Stack Chart

5.4 *PRODUCTIVE STATE* — A period of time (productive time) when the equipment is performing its intended function. The productive state includes:

- Regular production (including loading and unloading of product)
- Work for third parties
- Rework

- Engineering runs done in conjunction with production; may or may not be product units (e.g., split lots and new applications)

5.5 *STANDBY STATE* — A period of time (standby time), other than non-scheduled time, when the equipment is in a condition to perform its intended function, chemicals and facilities are available, but it is not operated. The standby state includes:

- No operator available (including breaks, lunches, and meetings)
- No product available (including no product due to lack of available support equipment, such as metrology tools)
- No support tools (e.g., cassettes, wafer carriers, probe cards)
- No input from external automation systems (i.e., host)

5.6 *ENGINEERING STATE* — A period of time (engineering time) when the equipment is in a condition to perform its intended function (no equipment or process problems exist), but is operated to conduct engineering experiments. The engineering state includes:

- Process engineering (e.g., process characterization)
- Equipment engineering (e.g., equipment evaluation)
- Software engineering (e.g., software qualification)

5.7 *SCHEDULED DOWNTIME STATE* — A period of time (scheduled downtime) when the equipment is not available to perform its intended function due to planned downtime events. The scheduled downtime state includes:

- Maintenance delay
- Production test
- Preventive maintenance
- Change of consumables/chemicals
- Setup
- Facilities-related downtime

5.7.1 *Maintenance Delay* — A period during which the equipment cannot perform its intended function because it is waiting for either user or supplier personnel or parts (including consumables/chemicals) associated with maintenance. Maintenance delay may also be due to an administrative decision to leave the equipment down and postpone maintenance.



NOTE 4: Maintenance delays may occur at any time in the maintenance process. These should be tracked separately from maintenance time. Delay time is included in time off-line, but not in time to repair (see Section 6.3 Equipment Maintainability).

5.7.2 Production Test — The planned interruption of equipment availability for evaluation of product or non-product units, as defined in the specifications of equipment operation, to confirm that the equipment is performing its intended function within specifications. It does not include testing that can be done in parallel with, or transparent to, the running of production, nor does it include any testing done following a preventive maintenance, setup, or repair procedure.

5.7.3 Preventive Maintenance — The sum of:

- **Preventive action:** A predefined maintenance procedure (including equipment ramp-down and ramp-up), at scheduled intervals, designed to reduce the likelihood of equipment failure during operation. Scheduled intervals may be based upon time, equipment cycles, or equipment conditions.
- **Equipment test:** The operation of equipment to demonstrate equipment functionality; (e.g., system reaches base pressure, wafers transfer without problem, gas flow is correct, plasma ignites, source reaches specified power).
- **Verification run:** The processing and evaluation of units after preventive action to establish that the equipment is performing its intended function within specifications.

NOTE 5: Equipment suppliers are responsible for specifying a preventive maintenance program to achieve a predetermined equipment performance level. Users are obligated to identify any deviation from the recommended program if they expect the supplier to meet or improve that performance level.

5.7.4 Change of Consumables/Chemicals — The scheduled interruption of operation to replenish the raw materials of semiconductor processing. It includes changes of gas bottles, acids, targets, sources, etc., and any purging, cleaning, or flushing normally associated with those changes. It does not include delays in obtaining those consumables/chemicals.

5.7.5 Setup — The sum of:

- **Conversion:** The time required to complete an equipment alteration necessary to accommodate a change in process, product, package configuration, etc. (excluding modifications, rebuilds, and upgrades).
- **Equipment test:** The operation of equipment to demonstrate equipment functionality; (e.g., system reaches base pressure, wafers transfer without

problem, gas flow is correct, plasma ignites, source reaches specified power).

- **Verification run:** The processing and evaluation of units after conversion to establish that equipment is performing its intended function within specifications.

NOTE 6: Equipment suppliers are responsible for providing procedures which achieve setup conversion and testing within predetermined specifications. Users are obligated to identify any deviation from the procedures if they expect the supplier to make setups fall within those specifications.

5.7.6 Facilities-Related Downtime — A period of time when the equipment cannot perform its intended function solely as a result of out of specification facilities. Those facilities include:

- Environmental (e.g., temperature, humidity, vibration, particle count)
- House hookups (e.g., power, cooling water, house gases, exhaust, LN2)
- Communications links with other equipment or host computers
- Communications links with hosts

5.7.6.1 Any downtime created by the items listed above shall be included in facilities-related downtime. For example, if, as a result of a scheduled fifteen minute power outage an otherwise unnecessary cryo pump regeneration is needed, all time required to return the equipment to a condition where it can perform its intended function is included in facilities-related downtime.

5.8 UNSCHEDULED DOWNTIME STATE — A period of time (unscheduled downtime) when the equipment is not in a condition to perform its intended function due to unplanned downtime events:

- Maintenance delay
- Repair
- Change of consumables/chemicals
- Out-of-spec input
- Facilities-related downtime

5.8.1 Maintenance Delay — A period during which the equipment cannot perform its intended function because it is waiting for either user or supplier personnel or parts (including consumables/chemicals) associated with maintenance. Maintenance delay may also be due to an administrative decision to leave the equipment down and postpone maintenance.

NOTE 7: Maintenance delays may occur at any time in the maintenance process. These should be tracked separately from



maintenance time. Delay time is included in time off-line, but not in maintenance time (see Section 6.4 Equipment Maintainability).

5.8.2 *Repair time* — The sum of:

- **Diagnosis:** The procedure of identifying the source of an equipment problem or failure.
- **Corrective action:** The maintenance procedure (including equipment ramp-down and ramp-up, re-booting, resetting, recycling, restarting, reverting back to a previous software version, etc.) employed to address an equipment failure and return the equipment to a condition where it can perform its intended function.
- **Equipment test:** The operation of equipment to demonstrate equipment functionality (e.g., system reaches base pressure, wafers transfer without problem, gas flow is correct, plasma ignites, source reaches specified power).
- **Verification run:** The processing and evaluation of units after corrective action to establish that the equipment is performing its intended function within specifications.

5.8.3 *Change of Consumables/Chemicals* — The unscheduled interruption of operation to replenish the raw materials of semiconductor processing. It includes changes of gas bottles, acids, targets, sources, etc., and any purging, cleaning, or flushing normally associated with those changes. It does not include delays in obtaining these consumables/chemicals.

5.8.4 *Out-of-Spec Input* — A period when the equipment cannot perform its intended function solely as a result of problems created by out-of-specification or faulty inputs. Those inputs include:

- Support tools (e.g., warped cassettes or wafer carriers, faulty probe cards, reticles)
- Product (e.g., upstream process/product problems, warped wafers, contaminated wafers, warped lead frames)
- Test data (e.g., metrology tool out of calibration, misread charts, erroneous data interpretation/entry)
- Consumables/chemicals (e.g., contaminated acid, leaky target bond, degraded photo resist, degraded mold compound)

5.8.4.1 Any downtime created by the items listed above shall be included in out-of-specification input downtime. For example, if, as a result of an intermittent probe card short, a prober/tester system is put down for repair, all downtime incurred prior to identifying the

problem is re-categorized as out-of-specification input downtime.

5.8.5 *Facilities-Related Downtime* — A period of time when the equipment cannot perform its intended function solely as a result of out-of-specification facilities. Those facilities include:

- Environmental (e.g., temperature, humidity, vibration, particle count)
- House hookups (e.g., power, cooling water, house gases, exhaust, LN2)
- Communications links with other equipment or host computers
- Communications links with hosts

5.8.5.1 Any downtime created by the items listed above shall be included in facilities-related downtime. For example, if, as a result of an unscheduled fifteen minute power outage, an otherwise unnecessary cryo pump regeneration is needed, all time required to return the equipment to a condition where it can perform its intended function is included in facilities-related downtime.

5.9 *NON-SCHEDULED STATE* — A period of time (non-scheduled time) when the equipment is not scheduled to be utilized in production, such as unworked shifts, weekends, and holidays (including shutdown and start-up).

5.9.1 If equipment is out of the production plan due to off-line training or an installation, modification, rebuild, or upgrade (hardware or software) that cannot be accommodated by the regular preventive maintenance schedule, its status is the non-scheduled state. This includes any qualification time required to bring the equipment to a condition where it can perform its intended function from one of these states.

5.9.2 Any maintenance done to equipment during these periods cannot be counted in the non-scheduled state, since all maintenance must fall into either scheduled or unscheduled downtime (this includes automatic maintenance routines such as a programmed cryo pump regeneration).

5.9.3 By the same convention, any production or engineering work done during these periods must fall into either productive or engineering time (this includes unattended operation that may shut itself off “after hours”).

6 RAM Measurement

6.1 Reliability, availability, and maintainability are measures of equipment performance which have been used widely in industry for decades. This section



defines them for the semiconductor industry in a manner that is consistent with existing industrial standards. Along with the definitions for RAM are given indicators by which these measures can be quantified.

6.2 EQUIPMENT RELIABILITY — The probability that the equipment will perform its intended function, within stated conditions, for a specified period of time.

NOTE 8: Two different methods of measuring this are presented, productive time and equipment cycles:

- Productive time only considers what happens while making product (useful for manufacturing operation purposes).
- Equipment cycles take into account the wear and tear created by every machine cycle during all equipment states (useful for equipment reliability purposes).

6.2.1 MTBI_p — Mean (productive) time between interrupts; the average time the equipment performed its intended function between interrupts; productive time divided by the number of interrupts during that time. Only productive time is included in this calculation. Interrupts that occur when an attempt is made to change from any state to a productive state are included in this calculation. Using MTBI_p, therefore, requires that the user not only have the capability of capturing failure and assist information, but also tracking and categorizing total time accurately.

$$MTBI_p = \frac{\text{productive time}}{\# \text{ of interrupts that occur during productive time}}$$

6.2.2 MTBF_p — Mean (productive) time between failures; the average time the equipment performed its intended function between failures; productive time divided by the number of failures during that time. Only productive time is included in this calculation. Failures that occur when an attempt is made to change from any state to a productive state are included in this calculation. Using MTBF_p, therefore, requires that the user not only have the capability of capturing failure information, but also tracking and categorizing total time accurately.

$$MTBF_p = \frac{\text{productive time}}{\# \text{ of failures that occur during productive time}}$$

6.2.3 MTBA_p — Mean (productive) time between assists; the average time the equipment performed its intended function between assists; productive time divided by the number of assists during that time. Only

productive time is included in this calculation. Using MTBA_p, therefore, requires that the user not only have the capability of capturing assist information, but also of tracking and categorizing total time accurately.

$$MTBA_p = \frac{\text{productive time}}{\# \text{ of assists that occur during productive time}}$$

NOTE 9: Reliability can be measured using various factors such as equipment times, cycles, or states. The following paragraphs are two examples using cycles.

6.2.4 MCBI — Mean cycles between interrupts; the average number of equipment cycles between interrupts; total equipment cycles divided by the number of interrupts during those cycles (includes both product and non-product cycles). This calculation transcends equipment states to include all cycles that the system, or subsystem, being considered experiences. It does not require tracking equipment states, only equipment cycles and equipment interrupts.

$$MCBI = \frac{\text{total equipment cycles}}{\# \text{ of interrupts}}$$

6.2.5 MCBF — Mean cycles between failures; the average number of equipment cycles between failures; total equipment cycles divided by the number of failures during those cycles (includes both product and non-product cycles). This calculation transcends equipment states to include all cycles that the system, or subsystem, being considered experiences. It does not require tracking equipment states, only equipment cycles and equipment failures.

$$MCBF = \frac{\text{total equipment cycles}}{\# \text{ of failures}}$$

6.2.6 MCBA — Mean cycles between assists; the average number of equipment cycles between assists; total equipment cycles divided by the number of assists during those cycles (includes both product and non-product cycles). This calculation transcends equipment states to include all cycles that the system, or subsystem, being considered experiences. It does not require tracking equipment states, only equipment cycles and assists.

$$MCBA = \frac{\text{total equipment cycles}}{\# \text{ of assists}}$$

6.3 EQUIPMENT AVAILABILITY — The probability that the equipment will be in a condition to perform its intended function when required.